

General Description

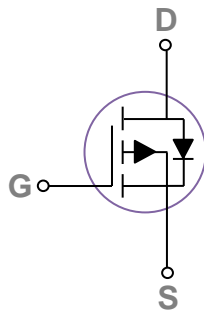
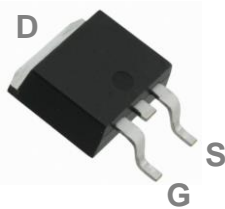
These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	R _{DS(ON)}	I _D
-30V	4.5mΩ	-85A

Features

- -30V, -85A, R_{DS(ON)} = 4.5mΩ @ V_{GS} = -10V
- Fast switching
- Green Device Available
- Suit for -4.5V Gate Drive Applications

TO252 Pin Configuration



Applications

- Motor Driver Applications
- POL Applications
- Load Switch
- LED Application

Absolute Maximum Ratings T_c=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-30	V
V _{GS}	Gate-Source Voltage	±20	V
I _D	Drain Current – Continuous (T _c =25°C)	-85	A
	Drain Current – Continuous (T _c =100°C)	-54	A
I _{DM}	Drain Current – Pulsed ¹	-340	A
EAS	Single Pulse Avalanche Energy ²	345	mJ
IAS	Single Pulse Avalanche Current ²	83	A
P _D	Power Dissipation (T _c =25°C)	104	W
	Power Dissipation – Derate above 25°C	0.83	W/°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction to Ambient	---	62	°C/W
R _{θJC}	Thermal Resistance Junction to Case	---	1.2	°C/W

Electrical Characteristics (T_J=25 °C, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	-30	---	---	V
ΔBV _{DSS} /ΔT _J	BV _{DSS} Temperature Coefficient	Reference to 25°C, I _D =-1mA	---	-0.03	---	V/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-30V, V _{GS} =0V, T _J =25°C	---	---	-1	uA
		V _{DS} =-24V, V _{GS} =0V, T _J =125°C	---	---	-10	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA

On Characteristics

R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =-10V, I _D =-30A	---	3.5	4.5	mΩ
		V _{GS} =-4.5V, I _D =-20A	---	5	7	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-1.2	-1.6	-2.2	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient		---	4	---	mV/°C
g _{fs}	Forward Transconductance	V _{DS} =-10V, I _D =-5A	---	25	---	S

Dynamic and switching Characteristics

Q _g	Total Gate Charge ^{3, 4}	V _{DS} =-15V, V _{GS} =-10V, I _D =-10A	---	108	150	nC
Q _{gs}	Gate-Source Charge ^{3, 4}		---	15	25	
Q _{gd}	Gate-Drain Charge ^{3, 4}		---	17.4	30	
T _{d(on)}	Turn-On Delay Time ^{3, 4}	V _{DD} =-15V, V _{GS} =-10V, R _G =6Ω I _D =-1A	---	28	56	ns
T _r	Rise Time ^{3, 4}		---	16	32	
T _{d(off)}	Turn-Off Delay Time ^{3, 4}		---	178	340	
T _f	Fall Time ^{3, 4}		---	72	140	
C _{iss}	Input Capacitance	V _{DS} =-25V, V _{GS} =0V, F=1MHz	---	6220	9000	pF
C _{oss}	Output Capacitance		---	782	1100	
C _{rss}	Reverse Transfer Capacitance		---	412	600	

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current	V _G =V _D =0V, Force Current	---	---	-85	A
I _{SM}	Pulsed Source Current		---	---	-170	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =-1A, T _J =25°C	---	---	-1	V
t _{rr}	Reverse Recovery Time	V _{GS} =0V, I _S =10A, di/dt=100A/μs	---	2.33	---	uS
Q _{rr}	Reverse Recovery Charge	T _J =25°C	---	52.9	---	uC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=83A., R_G=25Ω, Starting T_J=25°C.
3. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
4. Essentially independent of operating temperature.

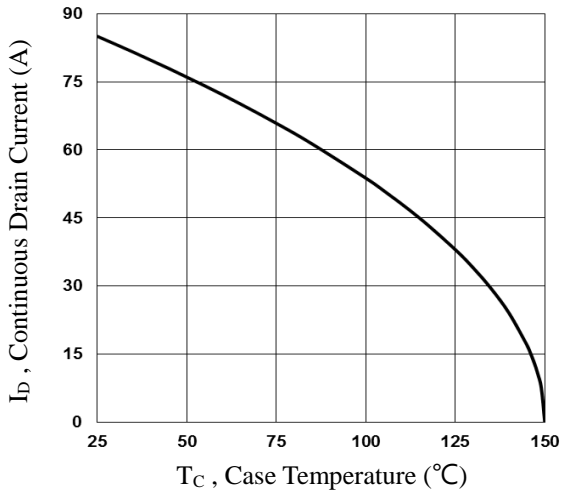


Fig.1 Continuous Drain Current vs. T_c

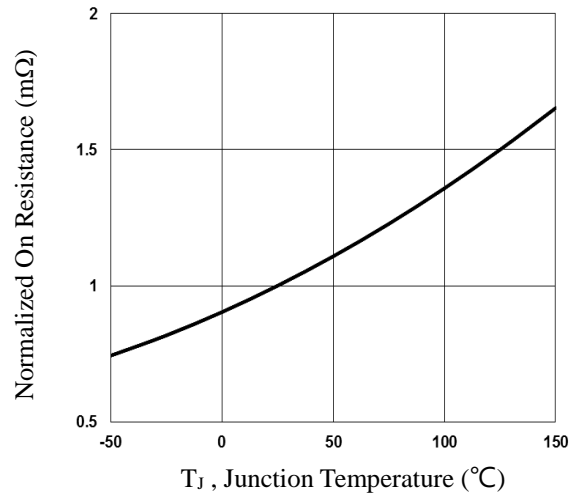


Fig.2 Normalized $R_{DS(on)}$ vs. T_j

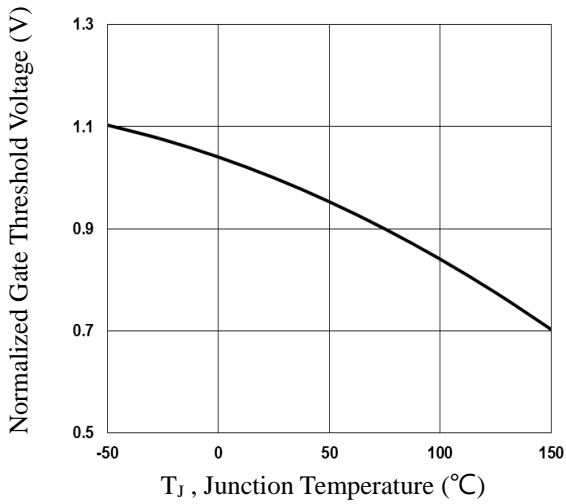


Fig.3 Normalized V_{th} vs. T_j

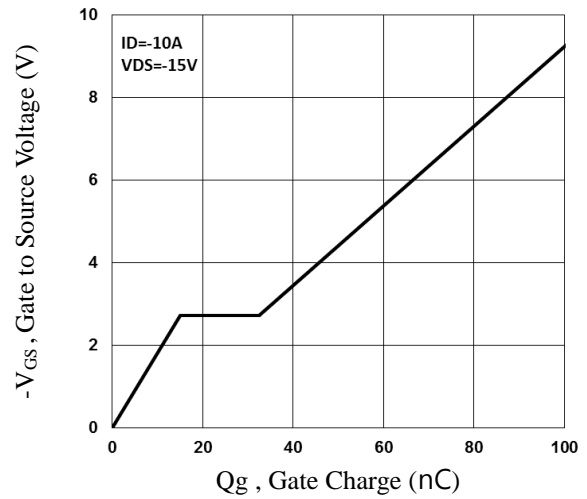


Fig.4 Gate Charge Waveform

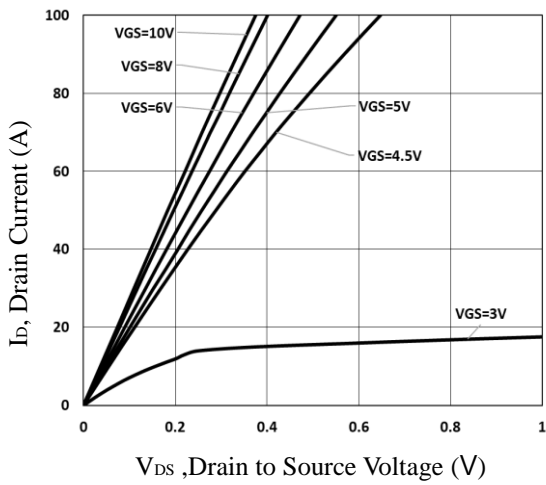


Fig.5 Typical Output Characteristics

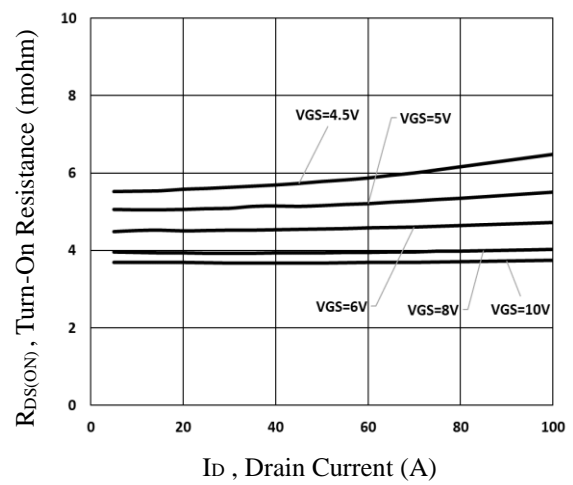


Fig.6 Turn-On Resistance vs. I_D

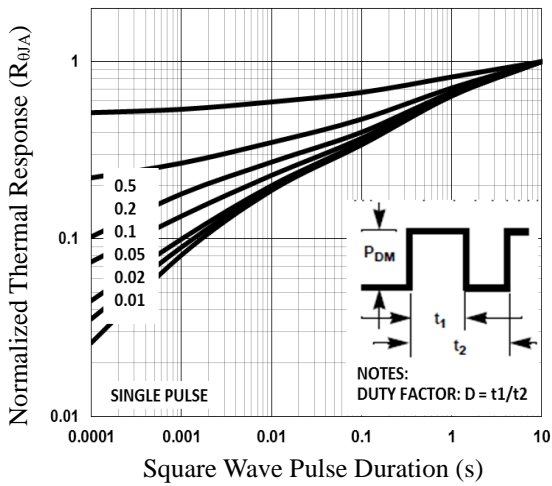


Fig.7 Normalized Transient Impedance

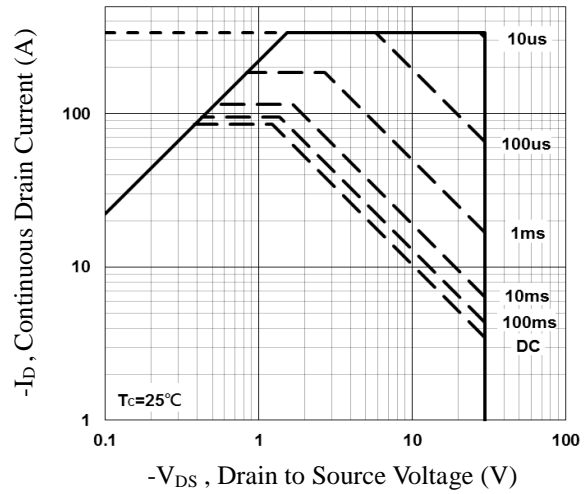


Fig.8 Maximum Safe Operation Area

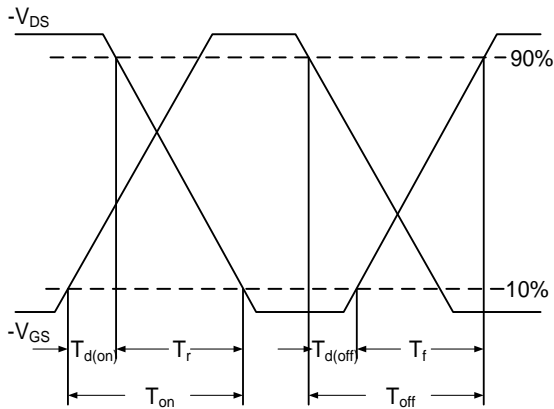


Fig.9 Switching Time Waveform

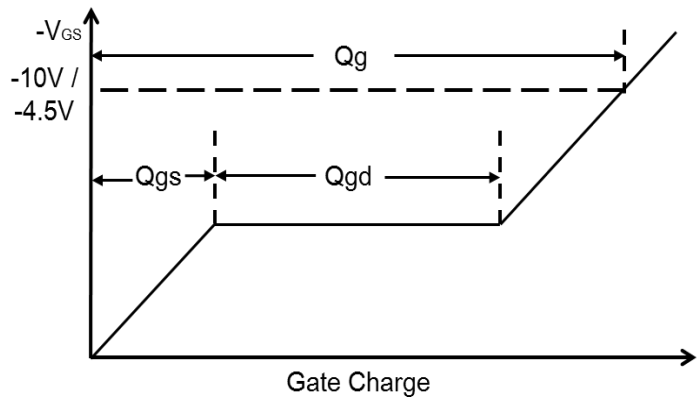
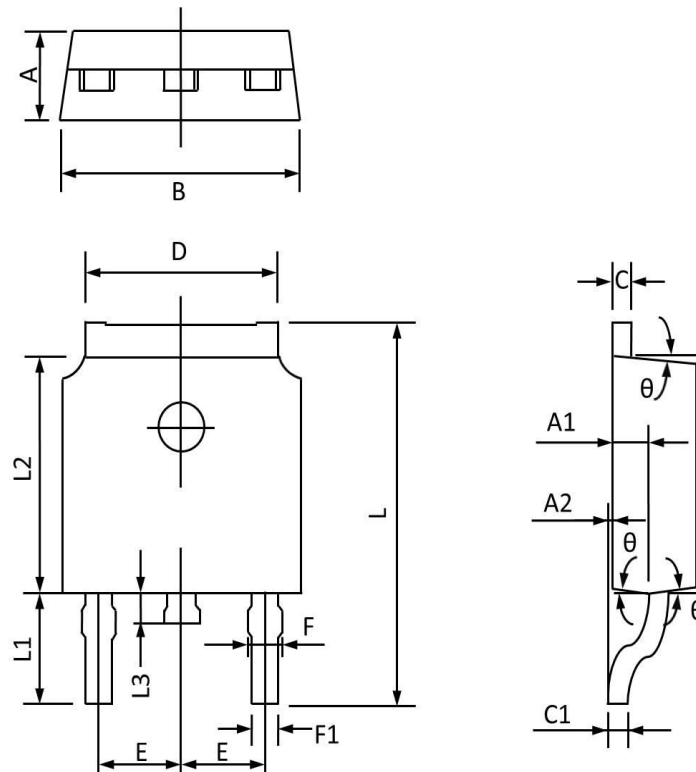


Fig.10 Gate Charge Waveform

TO252 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	2.400	2.200	0.094	0.087
A1	1.110	0.910	0.044	0.036
A2	0.150	0.000	0.006	0.000
B	6.800	6.400	0.268	0.252
C	0.580	0.450	0.023	0.018
C1	0.580	0.460	0.023	0.018
D	5.500	5.100	0.217	0.201
E	2.386	2.186	0.094	0.086
F	0.940	0.600	0.037	0.024
F1	0.860	0.500	0.034	0.020
L	10.400	9.400	0.409	0.370
L1	3.000	2.400	0.118	0.094
L2	6.200	5.400	0.244	0.213
L3	1.200	0.600	0.047	0.024
θ	9°	3°	9°	3°